

## VERSION SHOWING THE CHANGES TO THE CLAIMS

This listing replaces all prior listings.

### IN THE CLAIMS

Amend the claims as follows:

Claim 1, canceled.

2 (Previously presented). The electronic component as set forth in claim 13 wherein the through plating has a cross-sectional profile which comprises a truncated conical cross section free-standing raised portion relative to the first layer .

3 (Previously presented). The electronic component as set forth in claim 13 wherein the through plating comprises a truncated conical cross section profile free-standing raised portion of electrically conductive material and includes polyaniline, pedot, carbon black, graphite, electrically conducting silver and/or metal and/or a mixture thereof.

4(Previously presented). The electronic component as set forth in claim 13 wherein the component includes an electrically non-conducting insulating material wherein at least one of the plurality of layers and the non-conducting material is selected from the group consisting of polyhydroxystyrene, polymethylmethacrylate and/or polystyrene and/or a semiconducting material including polyalkylthiophene and/or polyfluorene and/or a mixture thereof.

5(Previously presented). The electronic component as set forth in claim 13

wherein the through-plating comprises a raised portion relative to the first layer that has a surface roughness which promotes ohmic contacting.

6(Previously presented). The electronic component as set forth in claim 13 wherein the disruption element manifests a chemical treatment of the first layer .

7(Previously presented). The electronic component as set forth in claim 13 wherein the first layer comprises a lower functional layer wherein the disruption element manifests a physical treatment of at least the lower functional layer .

8(Currently amended). The electronic component as set forth in one of claims [[1]]2-5 wherein the first layer comprises a lower functional organic layer .

9(Currently amended). The electronic component as set forth in one of claims [[1]]2-5 wherein the first layer comprises an organic functional layer wherein the disruption element manifests a locally restricted change in the surface energy of the first organic functional layer, at which substantially no wetting by a subsequently applied organic material of a subsequent functional layer is present .

10(Previously presented). The electronic component as set forth in claim 13 wherein the disruption element is on the first layer and comprises a chemical which provides a material residue on the first layer, at which prior to or after application of the plurality of layers, the disruption element is detectable by at least one of a material

residue[[s]], the shape of the disruption element , traces or a material on the first layer

11(Previously presented). The electronic component as set forth in claim 13 wherein the component comprises a plastic substrate which includes one of the following materials: PET, PP, PEN, polyimide, polyamide and coated paper.

12(Previously presented). A process for the production of at least one through-plating of an electronic component comprising:

forming a plurality of layers, a majority of which layers are of predominantly organic material and include an insulating layer, the forming of a first lower layer being followed by forming subsequent layers deposited sequentially on the first layer, the forming of the first layer including forming a disruption element on the first layer which element is arranged to result in a void in at least a first portion of the subsequently deposited layers, and then forming a through plating in the resulting void wherein at least a second portion of layers are ohmically intercoupled by the through plating .

13(Previously presented). An electronic product comprising:

a first layer;

a disruption element on a portion of the first layer over a given region of the first layer;

a plurality of layers on the first layer and overlying the disruption element on the first layer, at least a first portion of the plurality of layers comprises predominantly

organic material;

the disruption element being arranged to result in a void in a second portion of the plurality of layers in the area above the disruption element; and

a through plating in the resulting void for forming an electrical interconnection to at least two of the layers .

14 (Previously presented). The component of claim 13 wherein the through plating has a truncated conical cross section profile.

15 (Previously presented). The component of claim 13 wherein the through plating has a truncated conical cross section profile and is solid.

Claim 16, canceled.

17 (Currently amended). An electronic component comprising:

a first plurality of layers including a second plurality of predominately organic functional layers at least one of ~~the which~~ first layers is a first lower layer and at least one other of the first plurality of layers is a central layer; and

at least one through plating having a truncated conical cross-sectional profile which extends from the lower layer through at least the central layer transversely to the central layer, ~~and which the at least one through plating having a truncated conical cross section profile extending through plating extends~~ at least in part below the ~~at least one central functional layer~~ and is electrically coupled to at least two of said first

and second plurality of layers.

18 (Currently amended). The component of claim 17 wherein the through plating is electrically conductive and is ohmically coupled to ~~the~~ at least two of the layers.

19 (Currently amended). The component of claim 17 wherein ~~the~~ a third plurality of layers are on the first lower layer and form upper layers, the through~~[[ - ]]~~plating extending from the lower layer through at least one upper layer.

20 (Previously presented). The component of claim 17 wherein the through plating is electrically conductive.

21 (Currently amended). The component of claim 17 wherein the first and second plurality of layers form further lower layers and upper layers, the through plating decreasinges in diameter as ~~[[it]]~~ the through plating extends ~~away~~ from a lower layer to an upper layer.

22 (Currently amended). The component of claim 17 wherein the through plating extends through each of a further plurality of layers different than the first lower layer and is coupled to each of the of the further plurality of layers through which ~~[[it]]~~ the through plating extends.

23 (Currently amended). The component of claim 17 wherein the through plating

extends through each of a third plurality of layers different than the first lower layer and is coupled to the third plurality of layers through which ~~[[it]]~~ the through plating extends, the through plating being electrically conductive and at least two of said layers to which the through plating is coupled are electrically conductive and in ohmic contact with the through plating.

24 (Currently amended). The component of claim 17 wherein the through plating is ~~one~~ of solid and hollow.